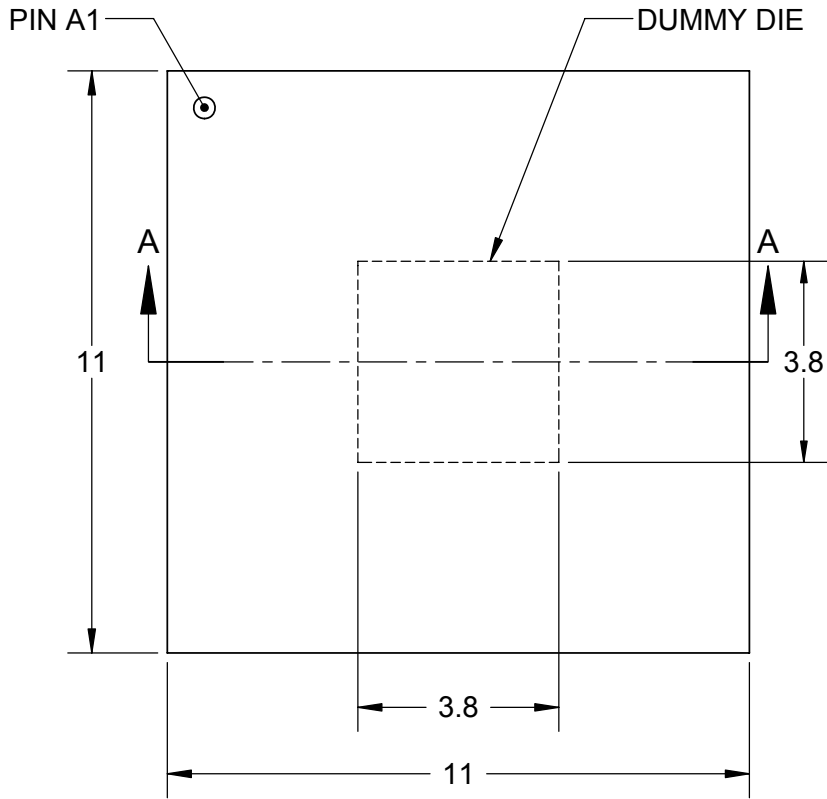
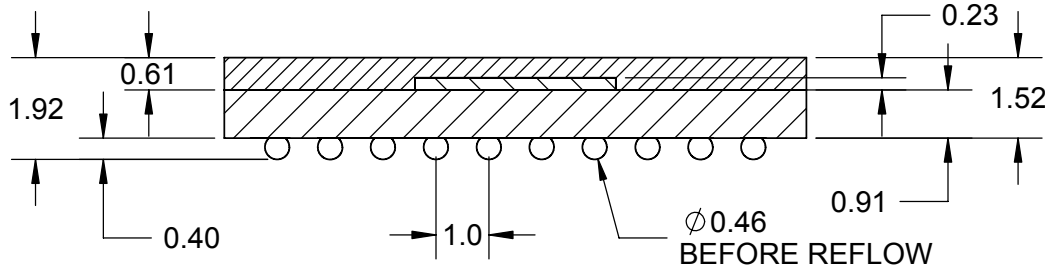
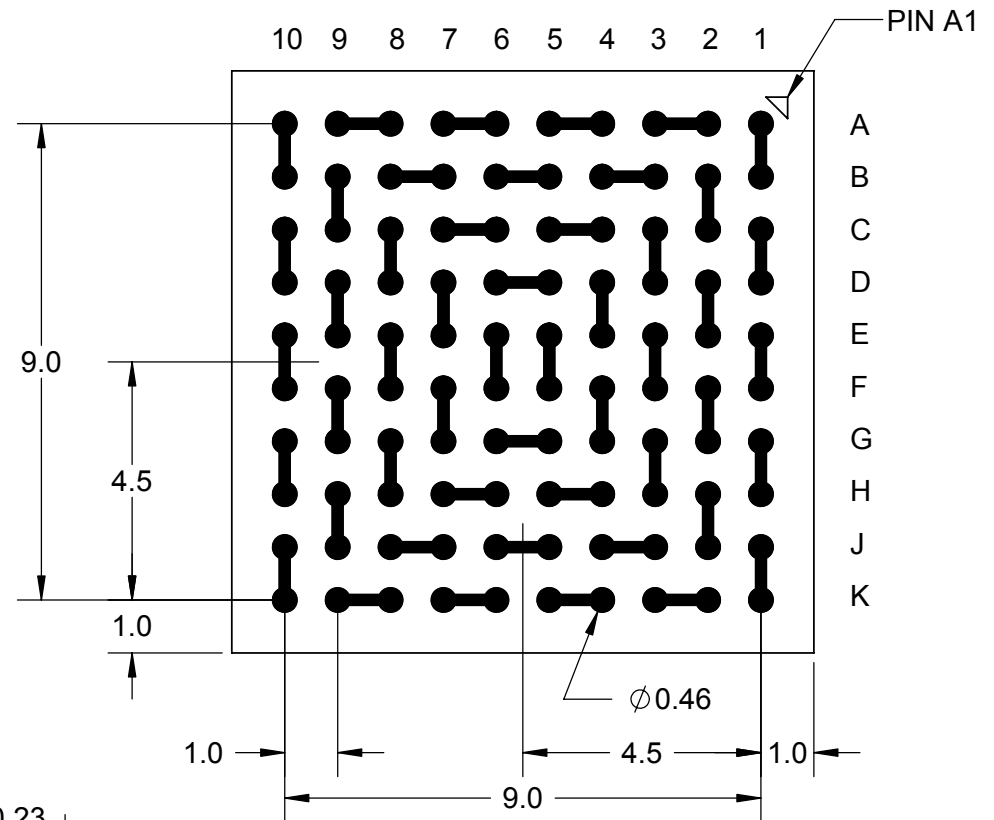


TOP VIEW



BALL VIEW




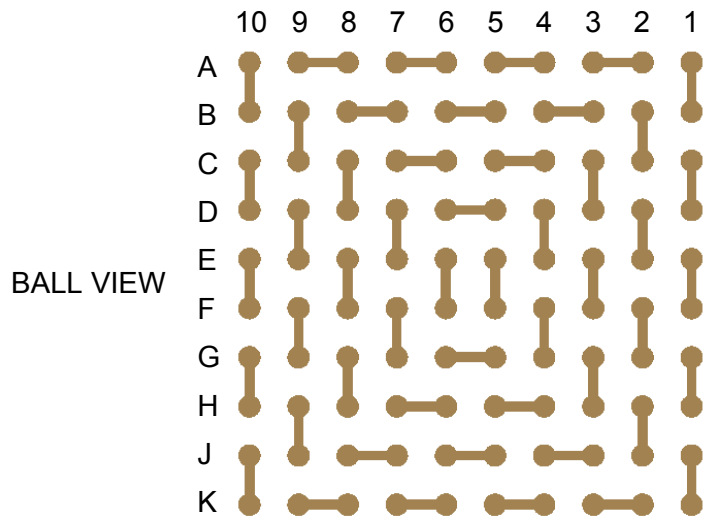
SECTION A-A

- Notes: (Unless Otherwise Specified).
 1) ALL DIMENSIONS ARE IN MM.
 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
 3) BALL DIAMETER (BEFORE REFLOW): 0.46mm [18 MIL].
 4) SOLDER MASK DEFINED PAD OPENING: 0.36mm [14 MIL].
 5) PAD Cu DIAMETER: 0.508mm [20 MIL].
 6) SUBSTRATE MATERIAL: FR4.
 7) DUMMY DIE: 0.230mm [9 MIL] THICK.
 8) DAISY CHAIN PATTERN (SEE PAGE 2).
 9) MSL-3 RECOMMEND BAKING 24 HOURS @ 125C TO REMOVE MOISTURE PRIOR TO SOLDERING TO PC BOARD.

PART NUMBER TABLE

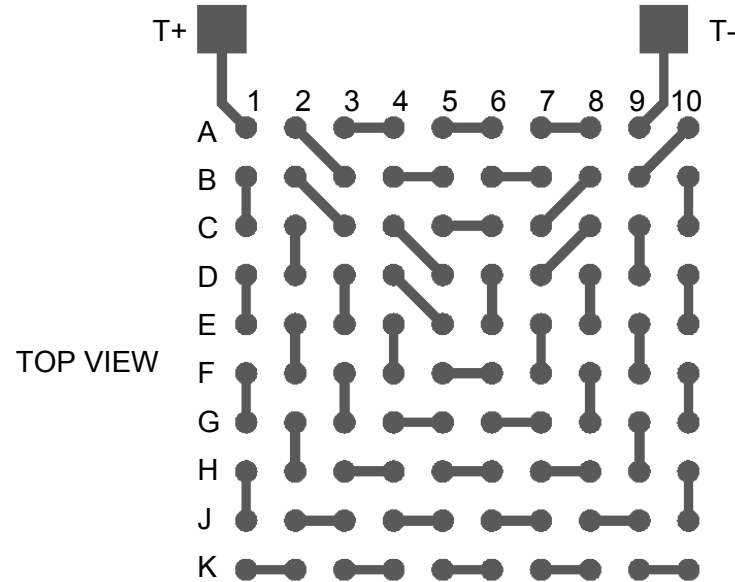
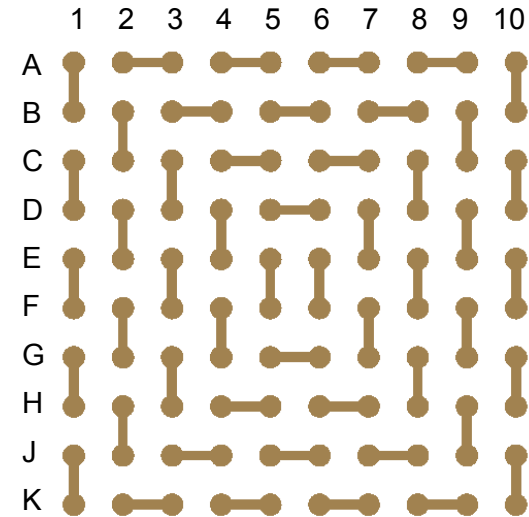
PART NUMER	BALL ALLOY	Pb-FREE	RoHS	Si DIE
BGA100T1.0C-DC109D	Sn96.5/Ag3.0/Cu0.5	YES	YES	YES
LGA100T1.0G-DC109D	NONE	YES	YES	YES
BGA100T1.0-DC109D	Sn63/Pb37	NO	NO	YES

APPROVALS	DATE				
DRAWN T.Au	9/4/2016				
ENG M. Hart	9/4/2016	TITLE		BGA100T1.0C-DC109D DAISY CHAIN DUMMY	
MFG		SCALE	SIZE	DRAWING NO.	REV
QA		7:1	A	511091	A
CUST		DO NOT SCALE DRAWING			SHEET 1 OF 3
REVISED					



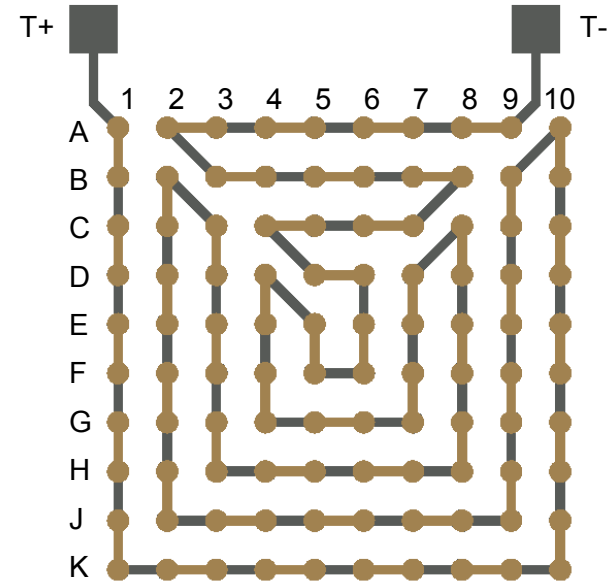
BALL VIEW

BOTTOM SIDE
(TOP X-RAY VIEW)



TOP VIEW

AFTER MOUNTING
TO TEST BOARD
(TOP X-RAY VIEW)

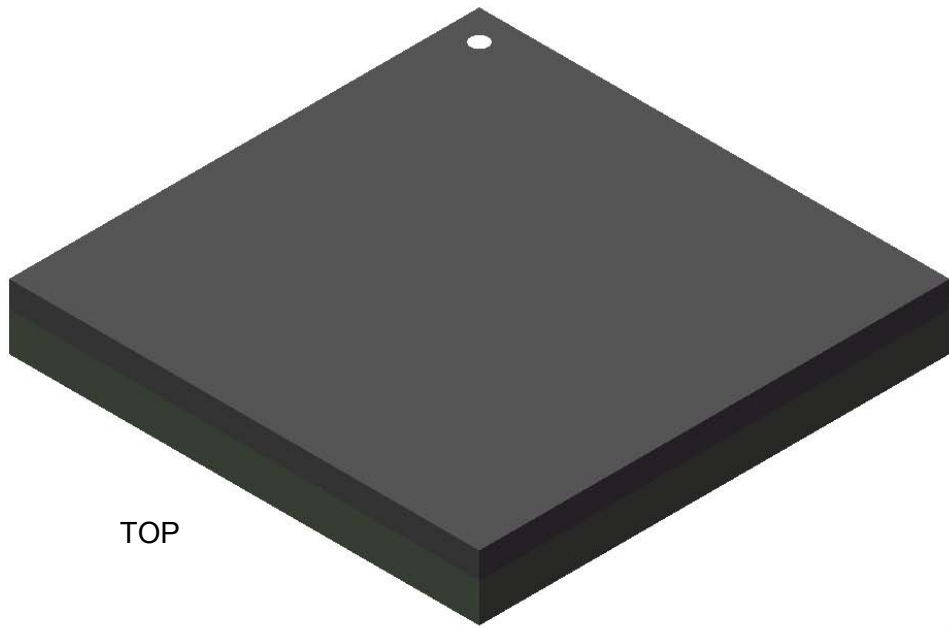


Notes:

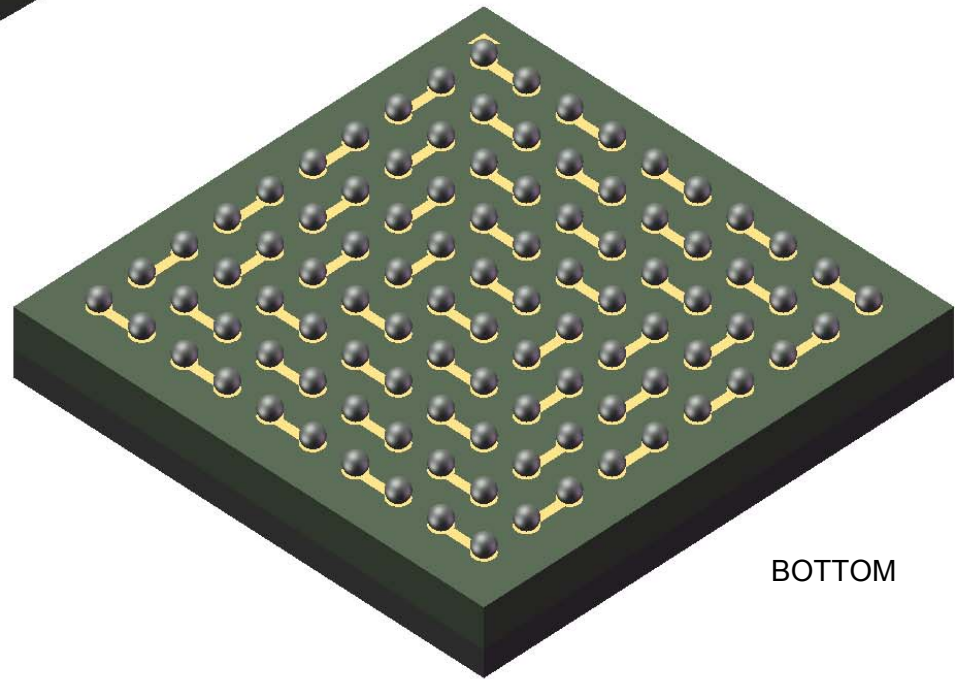
- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.508mm [20 MIL].
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.203mm [8 MIL].
- 4) SMD (SOLDER MASK DEFINED) PAD OPENING 0.36mm [14 MIL].

TopLine®			
TITLE		BGA100T1.0C-DC109D DAISY CHAIN DUMMY	
SCALE	SIZE	DRAWING NO.	REV
7:1	A	511091	A
DO NOT SCALE DRAWING			SHEET 2 OF 3

MODEL



TOP



BOTTOM

TopLine[®]

TITLE BGA100T1.0C-DC109D
DAISY CHAIN DUMMY

SCALE 8:1	SIZE A	DRAWING NO. 511091	REV A
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DO NOT SCALE DRAWING

SHEET 3 OF 3